

Dotted box > PCB manufacturer info

Layer Name	Type	Material	Thickness (mils)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mils	Not specified	1	0
F.Paste	Top Solder Paste		0 mils		1	0
F.Mask	Top Solder Mask	Not specified	0.3937 mils	Not specified	3.3	0
F.Cu	copper		1.37795 mils		1	0
Dielectric	core	FR4	59.44882 mils	Not specified	4.5	0.02
B.Cu	copper		1.37795 mils		1	0
B.Mask	Bottom Solder Mask	Not specified	0.3937 mils	Not specified	3.3	0
B.Paste	Bottom Solder Paste		0 mils		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mils	Not specified	1	0

BOARD CHARACTERISTICS

Copper Layer Count:

2

Board Thickness:

1.6000 mm

Board overall dimensions:

70.4850 mm x 76.2000 mm

Min track/spacing:

0.0000 mm / 0.0000 mm

Min hole diameter:

0.3000 mm

Copper Finish:

None

Impedance Control:

No

Castellated pads:

No

Plated Board Edge:

No

Edge card connectors:

No

Drill Map:

x

1.397mm / 0.0550" (20 holes)

O

1.800mm / 0.0709" (20 holes)

+

2.108mm / 0.0830" (8 holes)

□

3.175mm / 0.1250" (4 holes) (not plated)

NOTES

1.Layers: 2
2.Thickness: 1.6
3.Surface finish: HASL
4.Outer Copper Weight: 2oz
5.Via covering: Tented
6.Min hole size: .3mm
7.Gold Fingers: No
8.Castellated Holes: No
9.Edge Plating: No

LAYERS

User.1

Edge.Cuts

SPARTAN
ROBOTICS

Spartan Robotics

Sheet:
File: PowerDistribution.kicad_pcb

Title: **Power Distribution Board**

Size: BDate: 2024-10-12

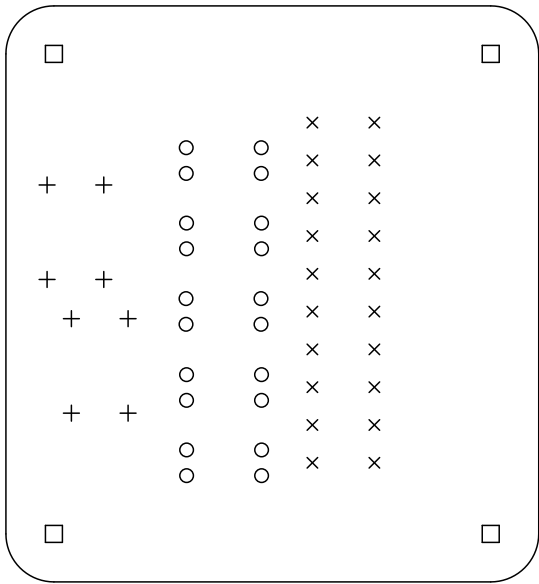
Rev: R2

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BOARD CHARACTERISTICS

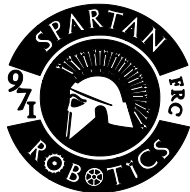
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Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		



Drill Map:

×	1.397mm	/	0.0550"	(20 holes)
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